

Date Created : 2007/11/12
Date Issued On : 2007/11/30
PCN# : Q4074601

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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Implementation of change:

Expected 1st Device Shipment Date: 2008/02/10

Earliest Year/Work Week of Changed Product: 0812

Change Type Description: Mold Compound

Description of Change (From): FPG 8L MLP3x3 package assembly at all FSC approved manufacturing location(s) (Carsem) using non Green mold compound as shown in table 1.

Description of Change (To): FPG 8L MLP 3x3 package assembly at all FSC approved manufacturing location(s) (Carsem) using Green mold compound as shown in table 2.

Reason for Change : Green initiative by Fairchild Semiconductor. Fairchild Semiconductor is dedicated to being a good corporate citizen. All Fairchild Semiconductor products are 2nd level interconnect lead-free and RoHS compliance. The referenced material changes have been made to provide a 'Full Green' (Halogen Free Flame Retardant) package. For additional details on the corporate wide green initiative please visit our Web site at:

<http://www.fairchildsemi.com/company/green/index.html> Manufacturing will occur at the same assembly facilities producing the current non-green products. Package outline drawings of the affected products remain un-changed. Green products will be fully compliant to all published data sheet specifications and will be interchangeable with current non-green product. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Qual/REL Plan Numbers : Q20070296

Qualification :

Qualification of Carsem FPG 8L MLP 3x3 with Green EMC (G600)

Change From

Table 1:

Assembly Site	Carsem
Lead Frame	DCI C194 with Ag Plated
Die Attach	84-1LMISNB
Wire	2 mils Au
Mold Compound	MP8000CSM-F1
Lead Finish	Tin plating (matte finish)

Change To

Table 2:

Assembly Site	Carsem
Lead Frame	DCI C194 with Ag Plated
Die Attach	84-1LMISNB
Wire	2 mils Au
Mold Compound	G600
Lead Finish	Tin plating (matte finish)

Qualification Stress Test and Sample Size Detail

Device #1	FDM6296
Package:	
#Leads:	

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
HAST2	X	JESD22-A110	85%RH, 110C, 24V	264		77
PRCL		MIL-STD-750-1036	Delta 100CC, 2 Min cycle	5000	10000	77
TMCL1	X	JESD22-A104	-65C, 150C	100	500	77

Device #2	FDMC2674
Package:	
#Leads:	

Precondition Description:

				Read-points	Sample

Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 40V	264			77
HTGB		JESD22-A108	150C, 20V	168	500	1000	77
HTRB		JESD22-A108	150C, 176V	168	500	1000	77
PRCL		MIL-STD-750-1036	Delta 100CC, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #3	FDMC8854
Package:	-1
#Leads:	-1

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 24V	264			77
HTGB		JESD22-A108	150C, 20V	168	500	1000	77
HTRB		JESD22-A108	150C, 24V	168	500	1000	77
PRCL		MIL-STD-750-1036	Delta 100CC, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Product Id Description : This forecast notification covers Fairchild Semiconductor FPG 8L MLP 3x3 packages. For a complete listing of products covered in this PCN release, please refer to the Affected FSID listing.

Affected FSIDs :

FDM3300NZ	FDM3300NZ_NL	FDM3622
FDM3622_NL	FDM6296	FDM6296_NL
FDMC2523P	FDMC2610	FDMC2674
FDMC3300NZA	FDMC5614P	FDMC8554
FDMC8854	FDMC8878	FDMC8878_NBSE003